



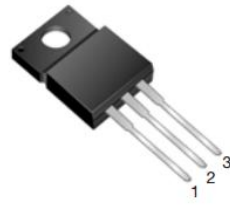
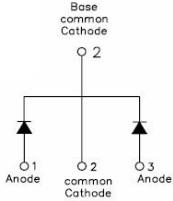
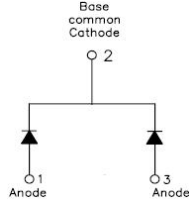
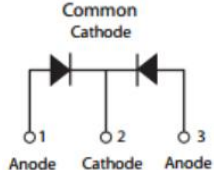
ST30100C/STB30100C/STF30100C SCHOTTKY RECTIFIER

Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Features

- 150 °C T_J operation
- Ultralow forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Trench MOS Schottky technology
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

ST30100C	STB30100C	STF30100C
		
		
TO-220AB	D ² PAK	ITO-220AB

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage	V _{RRM}	-	100	V
Working Peak Reverse Voltage	V _{RWM}			
DC Blocking Voltage	V _R			
Average Rectified Forward Current	I _{F(AV)}	50% duty cycle @T _c =100°C, rectangular wave form	15(Per Leg) 30(Per Device)	A
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	I _{FSM}	8.3ms, Half Sine pulse	200	A

Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop(Per Leg)*	V_{F1}	@ 5A, Pulse, $T_J = 25\text{ }^\circ\text{C}$	0.50	-	V
		@ 7.5A, Pulse, $T_J = 25\text{ }^\circ\text{C}$	0.61	-	
@ 15A, Pulse, $T_J = 25\text{ }^\circ\text{C}$		0.70	0.75		
	V_{F2}	@ 5A, Pulse, $T_J = 125\text{ }^\circ\text{C}$	0.46	-	V
		@ 7.5A, Pulse, $T_J = 125\text{ }^\circ\text{C}$	0.53	-	
		@ 15A, Pulse, $T_J = 125\text{ }^\circ\text{C}$	0.66	0.68	
Reverse Current(Per Leg)*	I_{R1}	@ $V_R = \text{rated } V_R$ $T_J = 25\text{ }^\circ\text{C}$	0.023	0.5	mA
	I_{R2}	@ $V_R = \text{rated } V_R$ $T_J = 125\text{ }^\circ\text{C}$	3.19	55	mA
Junction Capacitance(Per Leg)	C_T	@ $V_R = 5\text{V}$, $T_C = 25\text{ }^\circ\text{C}$ $f_{SIG} = 1\text{MHz}$	686	-	pF

* Pulse width < 300 μs , duty cycle < 2%

Thermal-Mechanical Specifications:

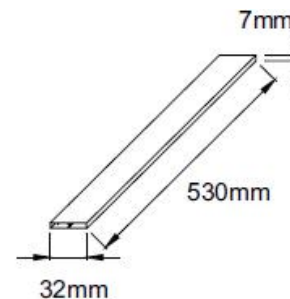
Characteristics	Symbol	ST30100C	STB30100C	STF30100C	Units
Junction Temperature	T_J	-55 to +150			$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to +150			$^\circ\text{C}$
Typical Thermal Resistance Junction to Case(Per Leg)	$R_{\theta JC}$	2.8	2.8	5.5	$^\circ\text{C/W}$

Tube Specification

Device	Package	Weight	Shipping
ST30100C	TO-220AB	2.0	50pcs / tube
STB30100C	D ² PAK	1.85	800pcs / reel
STF30100C	ITO-220AB	2.0	50pcs / tube

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Tube Specification(TO-220AB/ITO-220AB)



Ratings and Characteristics Curves

Figure 1
Typical Forward Characteristics

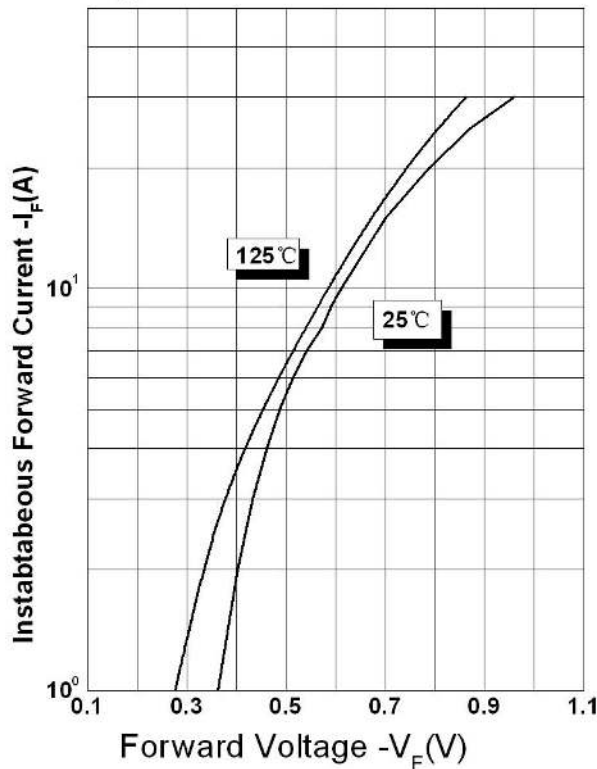


Figure 2
Typical Reverse Characteristics

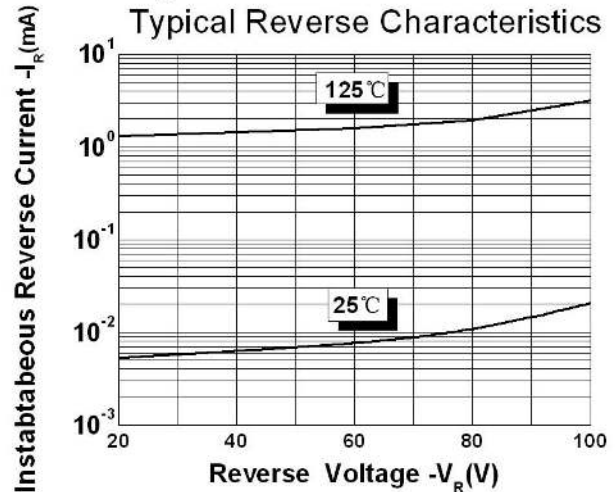
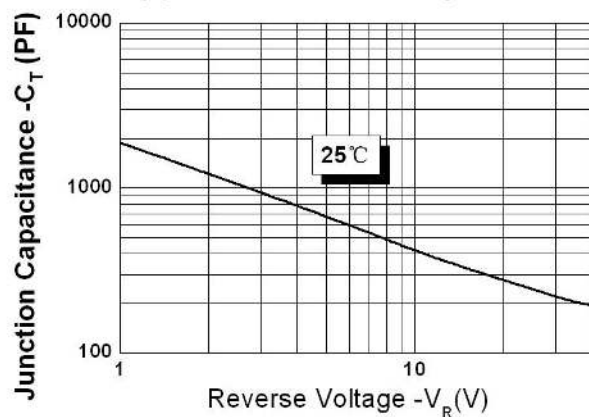
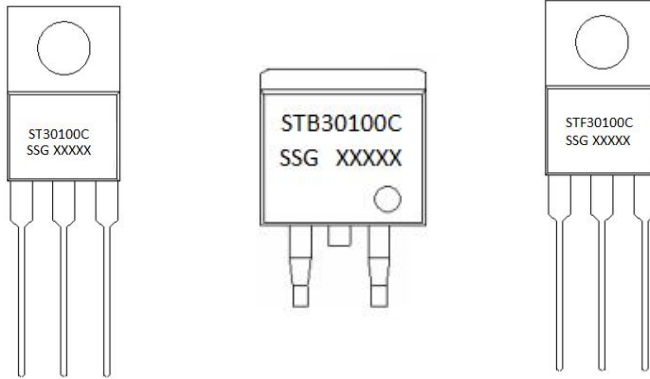


Figure 3
Typical Junction Capacitance



Marking Diagram

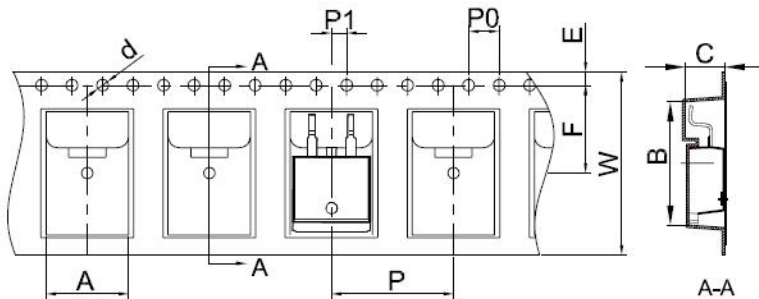


Where XXXXX is YYWWL

ST = Device Type
B/F = Package type
30 = Forward Current (30A)
100 = Reverse Voltage (100V)
C = Configuration
SSG = SSG
YY = Year
WW = Week
L = Lot Number

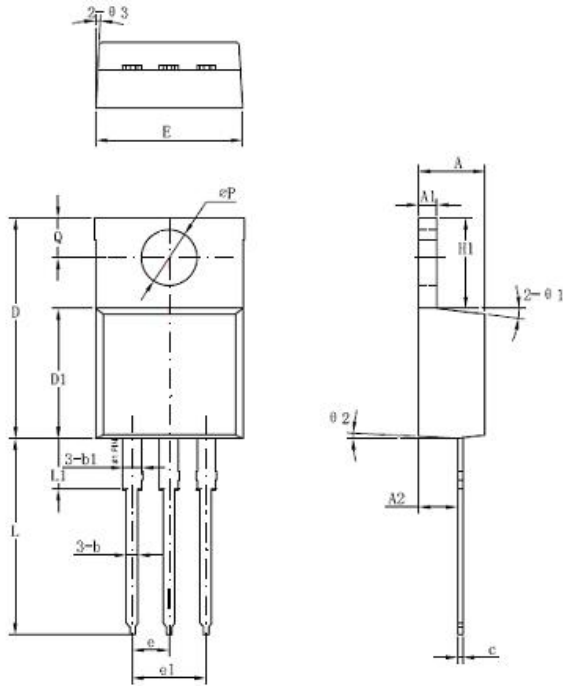
Cautions: Molding resin
Epoxy resin UL:94V-0

Carrier Tape Specification D2PAK



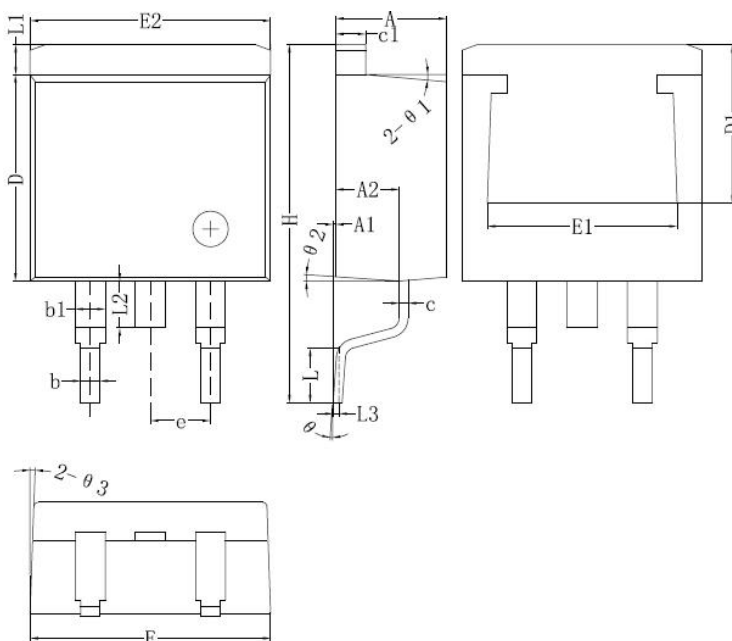
SYMBOL	Millimeters	
	Min.	Max.
A	10.70	10.90
B	16.03	16.23
C	5.11	5.31
d	1.45	1.65
E	1.65	1.85
F	11.40	11.60
P0	3.90	4.10
P	15.90	16.10
P1	1.90	2.10
W	23.90	24.30

Mechanical Dimensions TO-220AB



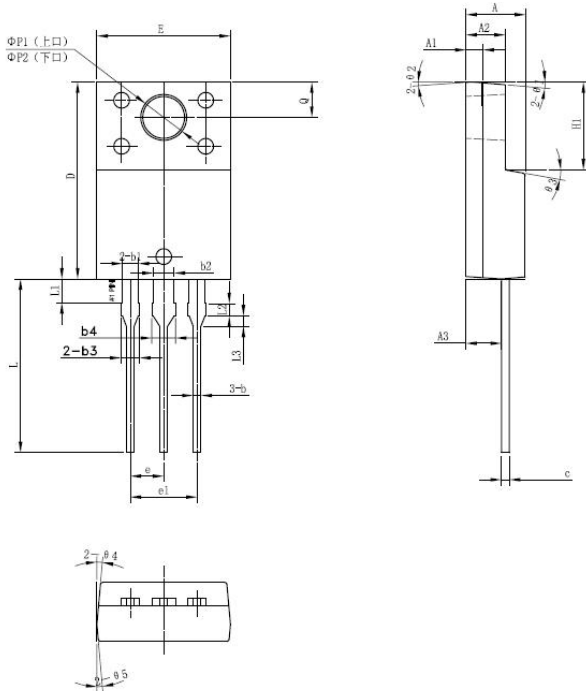
Symbol	Dimensions in millimeters		
	Min	Typical	Max
A	4.42	4.57	4.72
A1	1.17	1.27	1.37
A2	2.52	2.69	2.89
b	0.71	0.81	0.96
b1	1.17	1.27	1.37
c	0.31	0.38	0.61
D	14.94	15.24	15.54
D1	8.85	9.00	9.15
E	10.01	10.16	10.31
e		2.54	
e1	4.98	5.06	5.18
H1	6.04	6.24	6.44
L	12.7	13.56	13.80
L1	3.56	3.5	3.96
ΦP	3.74	3.84	4.04
Q	2.54	2.74	2.94
Q1		7°	
Q2		3°	
Q3		4°	

Mechanical Dimensions D²PAK



Symbol	Dimensions in millimeters		
	Min.	Typical	Max.
A	4.55	4.70	4.85
A1	0	0.10	0.25
A2	2.59	2.69	2.89
b	0.71	0.81	0.96
b1		1.27	
c	0.36	0.38	0.61
c1	1.17	1.27	1.37
D	8.55	8.70	8.85
D1	6.40		
E	10.01	10.16	10.31
E1	7.6		
E2	9.98	10.08	10.18
e		2.54	
H	14.6	15.1	15.6
L	2.00	2.30	2.70
L1	1.17	1.27	1.40
L2			2.20
L3		0.25BSC	
e	0	-	8°
e1		5°	
e2		4°	
e3		4°	

Mechanical Dimensions ITO-220AB



Symbol	Dimensions in millimeters		
	Min.	Typical	Max.
A	4.30	4.50	4.70
A1	1.10	1.30	1.50
A2	2.80	3.00	3.20
A3	2.50	2.70	2.90
b	0.50	0.60	0.75
b1	1.10	1.20	1.35
b2	1.50	1.60	1.75
b3	1.20	1.30	1.45
b4	1.60	1.70	1.85
c	0.50	0.60	0.75
D	14.80	15.00	15.20
E	9.96	10.16	10.36
e		2.55	
e1		5.10	
H1	6.50	6.70	6.90
L	12.70	13.20	13.70
L1	1.60	1.80	2.00
L2	0.80	1.00	1.20
L3	0.60	0.80	1.00
$\Phi P1$ (上孔)	3.30	3.50	3.70
$\Phi P2$ (下孔)	2.99	3.19	3.39
Q	2.50	2.70	2.90
$\Theta 1$		5°	
$\Theta 2$		4°	
$\Theta 3$		10°	
$\Theta 4$		5°	
$\Theta 5$		5°	



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